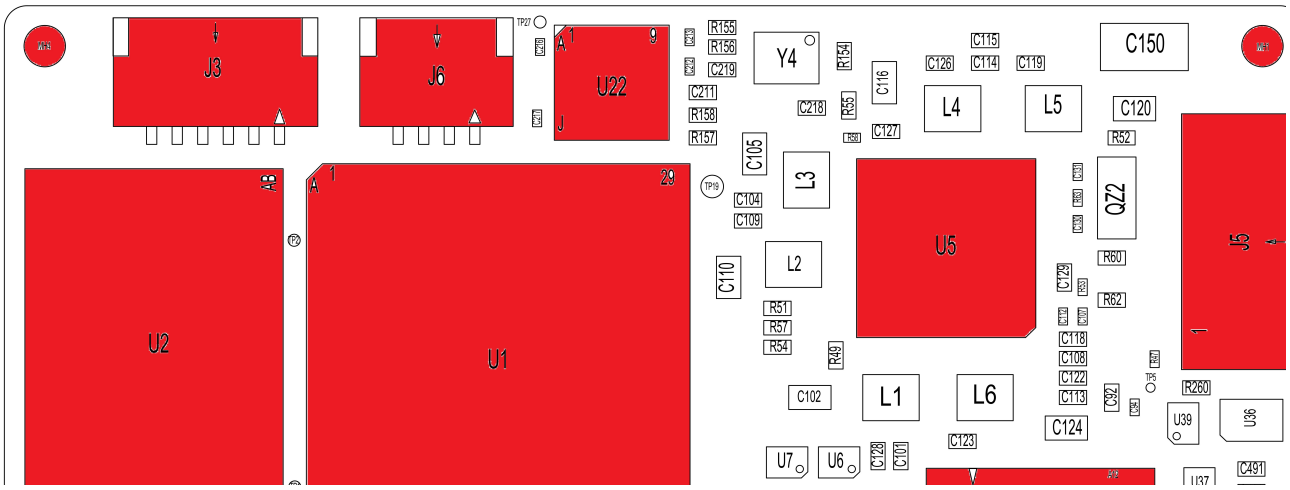
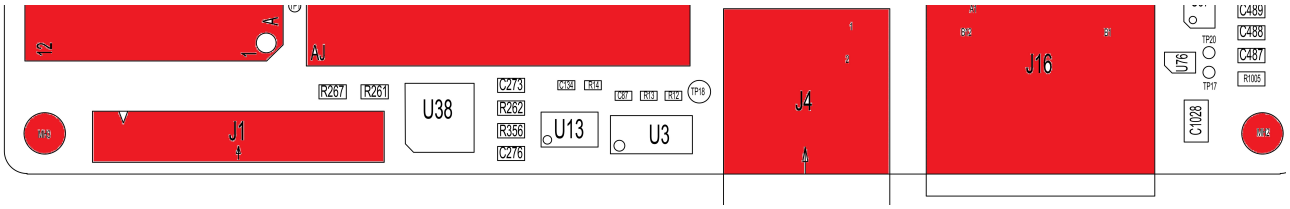
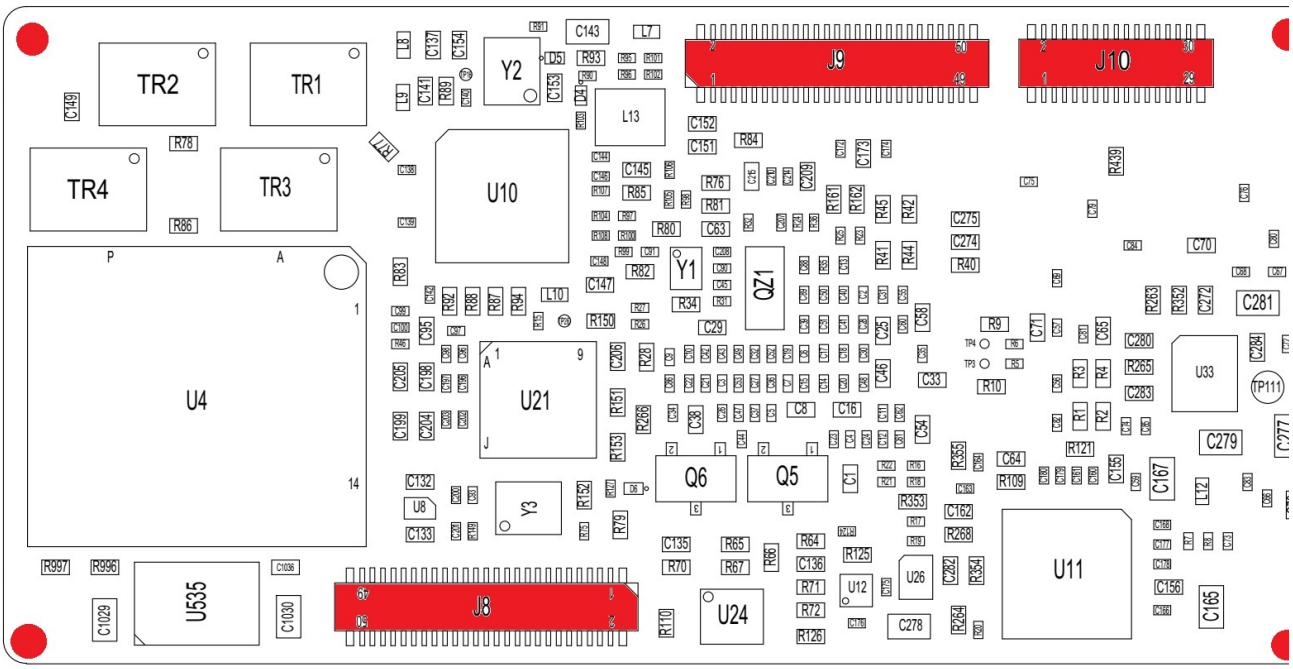
See below instructions:

- The Red areas on the Nn Main and HDMI files should be masked
- The flux removal, see attached, should be applied before coating
- The coating material should be a mixture of the materials defined in Versatill ZT and 1B31

Please also inform the customer that we’re using Aim Solder M8 solder paste.



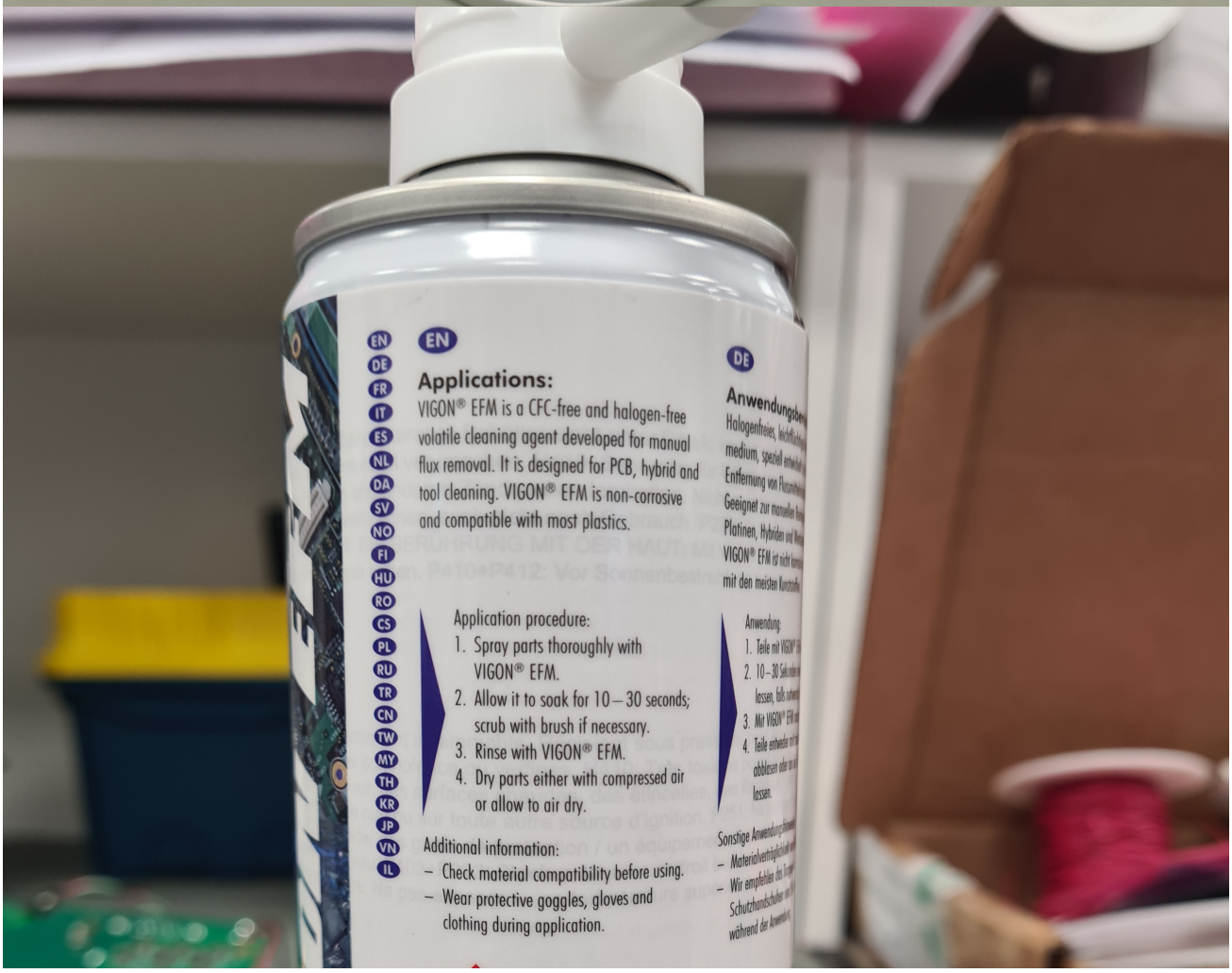




Versatill ZT 01-27-...DS.pdf

1B31.pdf

Removes
flux residues
Entfernt
Flussmittelrückstände
Elimine
les résidus de flux
Fluxes are rapidly
dissolved
Dries residue-free
Löst Flussmittel schnell an
Trocknet rückstandsfrei ab
Dissout rapidement le flux
Sèche sans résidus
VIGON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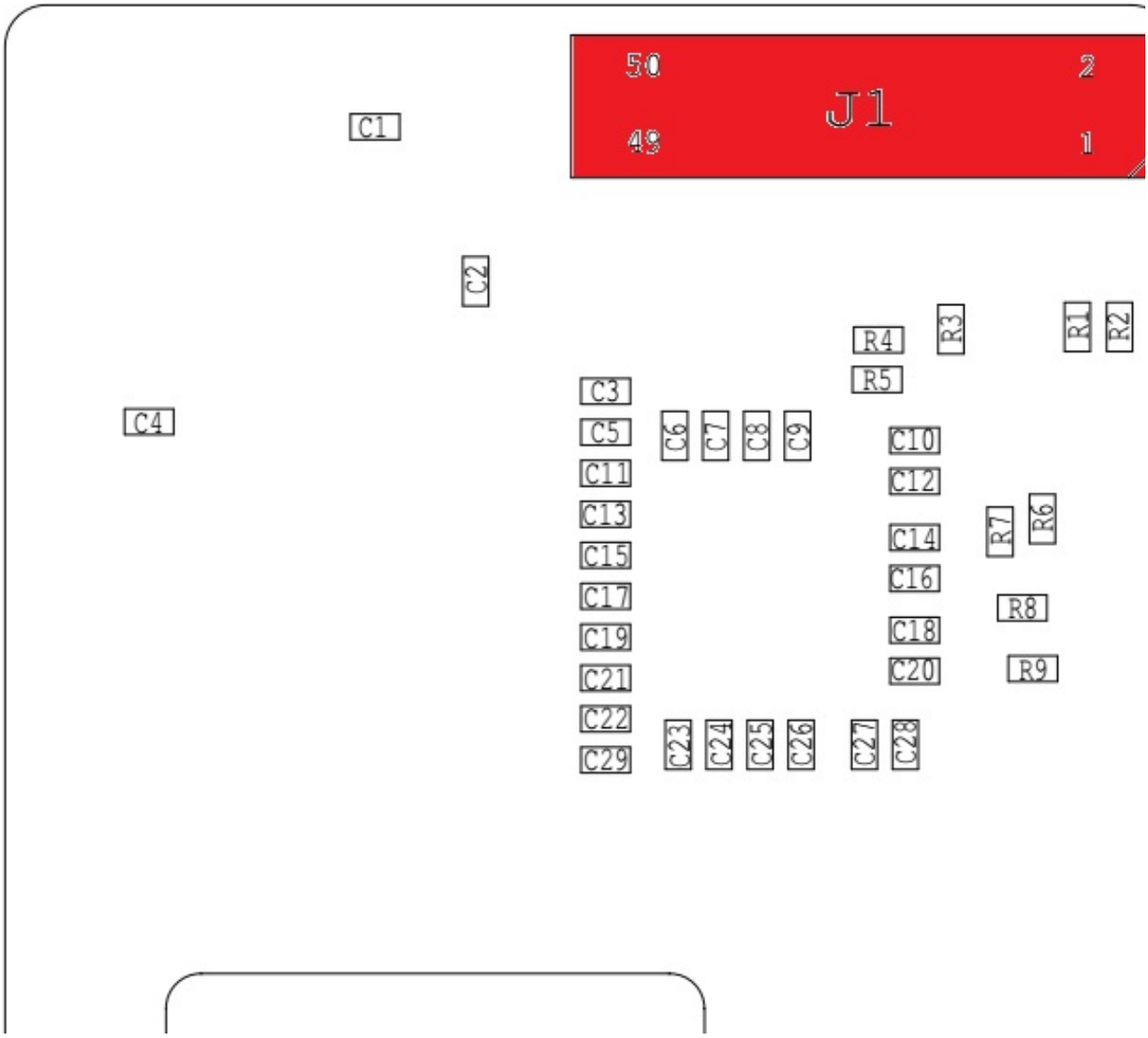
Applications:
VIGON® EFM is a CFC-free and halogen-free volatile cleaning agent developed for manual flux removal. It is designed for PCB, hybrid and tool cleaning. VIGON® EFM is non-corrosive and compatible with most plastics.
Application procedure:
1. Spray parts thoroughly with VIGON® EFM.
2. Allow it to soak for 10 – 30 seconds; scrub with brush if necessary.
3. Rinse with VIGON® EFM.
4. Dry parts either with compressed air or allow to air dry.
Additional information:
– Check material compatibility before using.
– Wear protective goggles, gloves and clothing during application.
DE

Gefahr, Danger, Pericolo, Peligro,
Perigo, Gevaar, Fare, Fara, Vaara,
Veszély, Pericol, Nebezpečí, Niebez-
pieczeństwo, Опасно, Tehlike, 危險,
危険, Bahaya, อันตราย, 위험, 危險,
Nguy hiểm, סכנה
Made in Germany by
ZESTRON
Bunsenstrasse 6, D-85053 Ingolstadt, Germany
Phone: +49 841 635-90 | Fax: +49 841 635-40
eMail: info@zestron.com | www.zestron.com
300 ml


50
2
J1
49
1
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